

Hirose Korea Board To Wire Connector

KN21-Series

1. Characteristic of Products ----- 2 page

2. Specifications & Formation of Products ----- 3 page

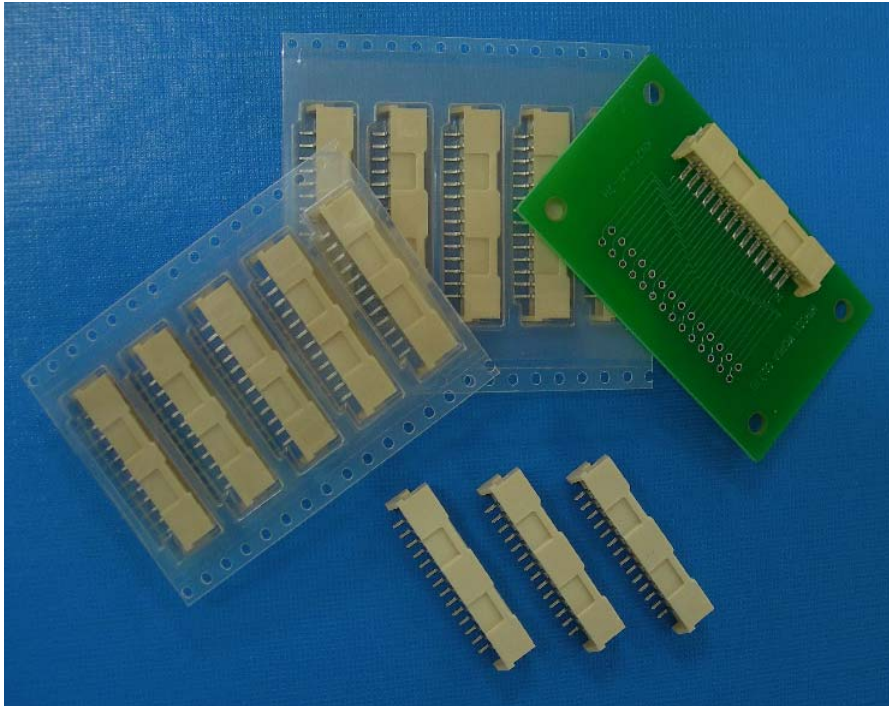
3. Details of Products ----- 4 ~ 5 page

No.	Products Name	NO of Contacts	Specification	page
1	KN21-12P-2H	12	Pitch 2mm , Height 5.5mm	4~5
2	KN21-14P-2H	14	Pitch 2mm, Height 5.6mm	4~5

4. Reflow profile ----- 6page

KN21 - SERIES

2mm PITCH, Board To Wire CONNECTOR



■ Features

1. Box(Four Wall) Type Pin Header

- The Pin Header has the box structure to prevent from being twisted and to prevent from contamination on contacts by soldering waste and flux .

2. Correspond to Automatic mounting

- The Pin Header has the vacuum mount face, so it is available in a surface mount config

3. Listed by UL, C-UL

■ Applications.

Inner connection as Board To Wire Connector FOR Electronic Equipment -LCD, PDP etc. for DISPLAY, note PC etc. mini Electronic Equipment.

■ Specifications

Rating	Current 2A AC, DC	Operating temperature range	Storage temperature range
	Voltage 100V AC	- 25 °C ~ + 85 °C	- 10 °C ~ + 60 °C

Item	Test Method	Condition
1. Insulation Resistance	1000MΩ Min	Measured at 500V DC
2. Withstand voltage	Neither shot or insulation breakdown	800V AC for 1 minute
3. Contact Resistance	10mΩ Max	Measured at 1mA(or 1,000Hz)
4. Mechanical operation	Contact Resistance : 20mΩ Max	30 Time insertions and extractions.
5. Moisture Resistance	Temperature : 40±2 °C	Contact Resistance : 20mΩ Max Insulation Resistance : 500MΩ Min
	Relative Humidity : 90~95%	
	Duration : 240Hr	
6. Resistance to Soldering heat	Reflow : 183 °C MIN. 90~120s, 250±5 °C 30±5s	No deformation of components affecting performance.

■ Plating specifications and row materials by parts

Part	Material	Finish	Remarks
CASE	POLYAMID	NATURAL(Beige)	UL94V-0
Contact	Brass	Tin plating over Ni	-
Metal Fitting	Brass	Tin plating over Ni	-

※ Since Satisfy with Reflow Temperature MAX 250 °C, Fit for use at Lead-free Soldering.

※ RoHS Compliant Suitable.

■ Formation of part number.

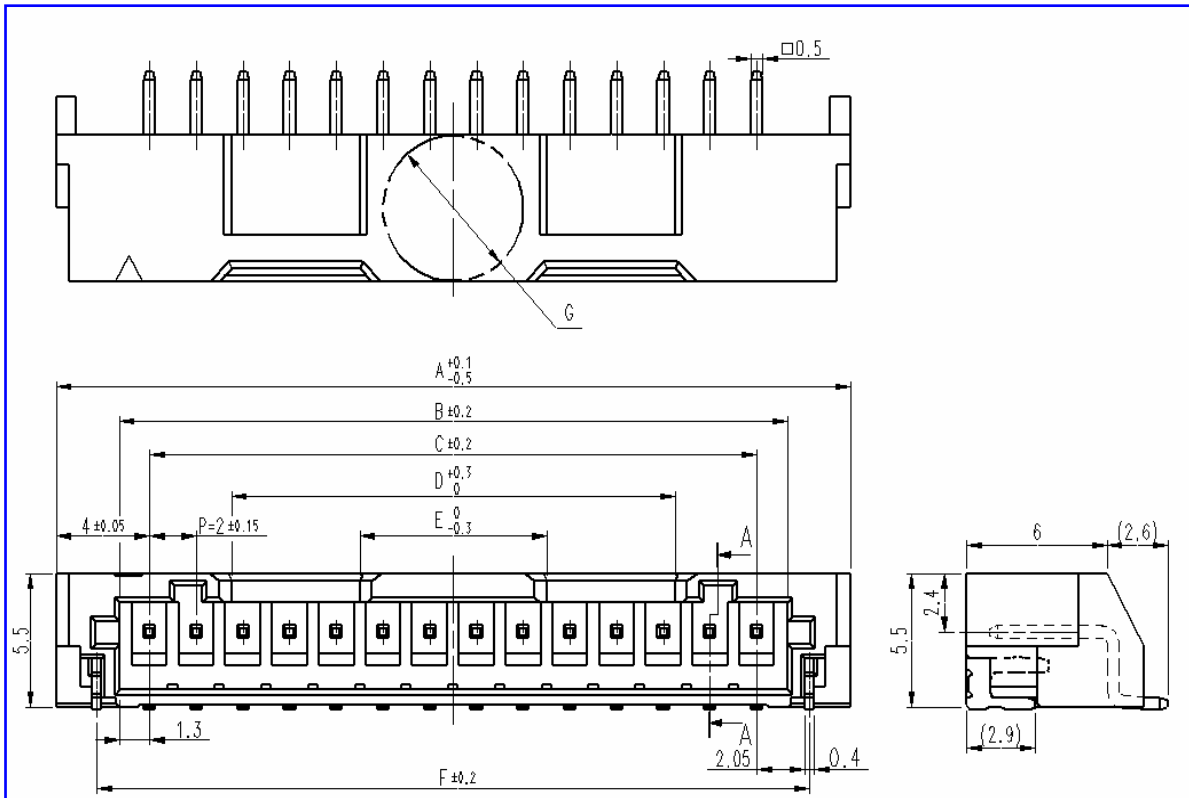
KN 21 # - ** P - 2 H

① ② ③ ④ ⑤ ⑥ ⑦

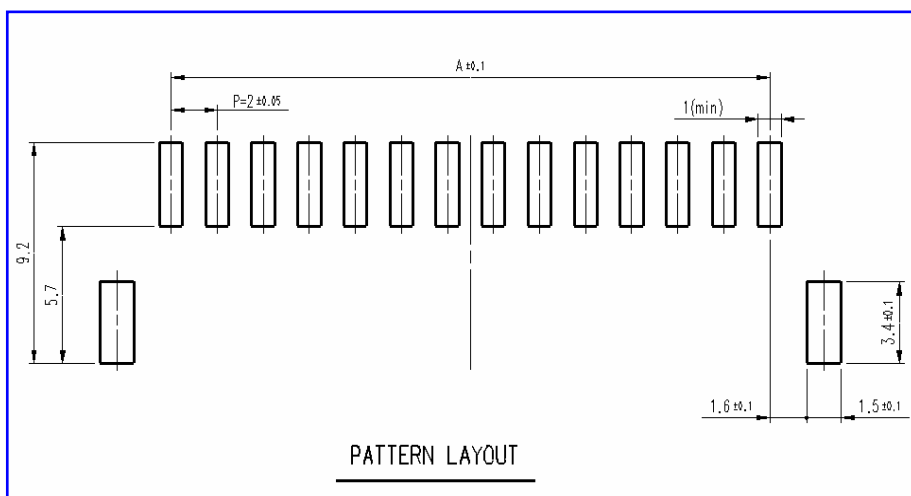
①	Serial Name	KN
②	Serial No.	21
③	Blank	Standard type
④	No of Contact	12.14 PIN
⑤	Connector type	P : Plug
⑥	Contact Pitch	2mm
⑦	Contact type	H(SMT horizontal mount type)

KN21-SERIES

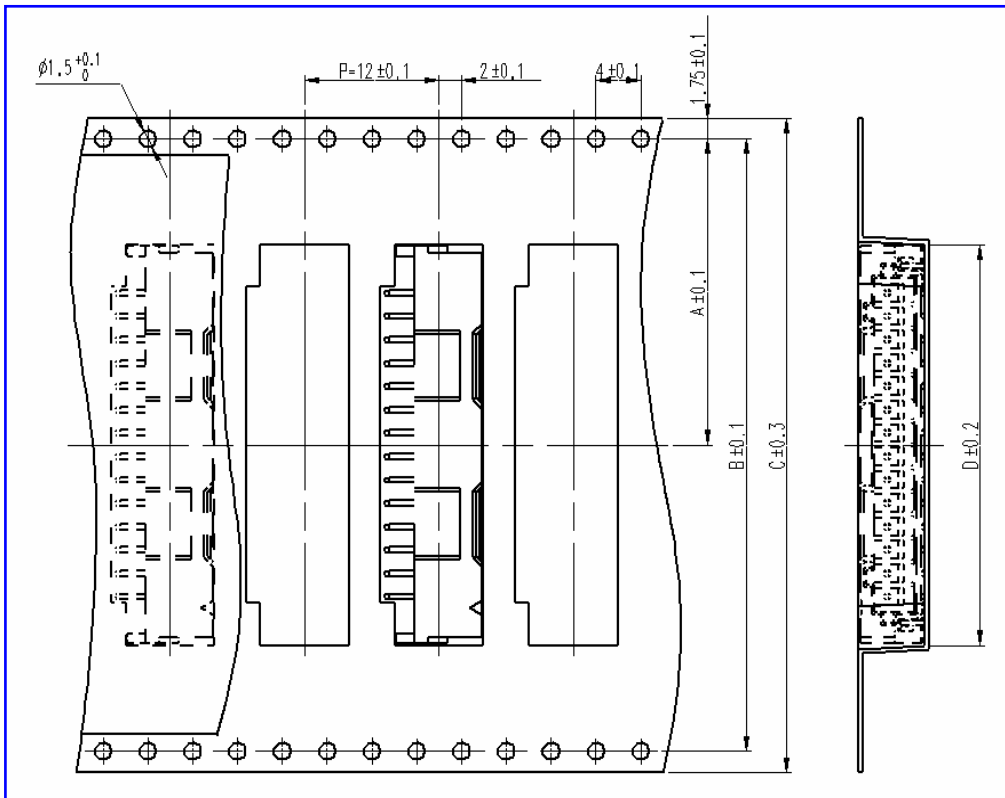
- DIMENSIONS



	A	B	C	D	E	F	G
12P	30	24.6	22	15	4.00	26.5	3.8
14P	34	28.6	26	19	4.00	30.5	6



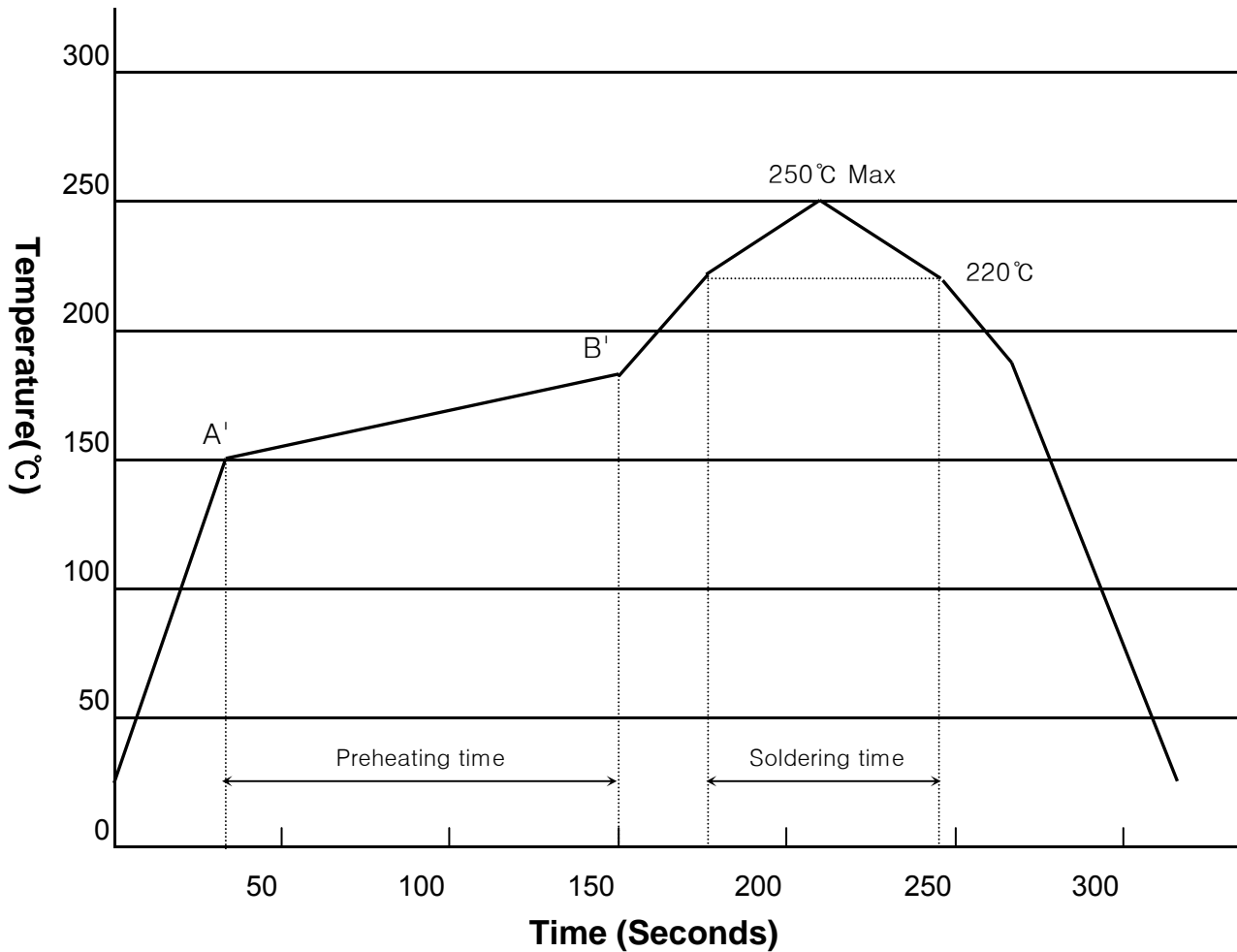
	A
12P	22
14P	26

- PACKING DIMENSIONS

	A	B	C	D	Package	Quantity
12P	20.2	40.4	44	30.3	Emboss Tape	1,000ea/Reel
14P	26.2	52.4	56	34.3	Emboss Tape	1,000ea/Reel

■ Reflow Profile

Using Lead-free Solder Paste



Recommended Application Conditions

Reflow System: IR reflow

Solder: Cream type Sn / 3 Ag / 0.5 Cu

Flux content 11%wt

Metal mask thickness: 0.15mm

Preheating time: 150°C~190°C, 90±30seconds

A'=150°C~170°C, B'=170°C~190°C

Soldering time: 250°C Max

220°C Min, 30~60 seconds